A06-013-476600-0A

Product Change Notice

Issue date: 01/22/2006

Change Type: Major

- To optimism capacity

Part(s) Affected:

Pkg Type	Avago Tech Part #
44L MQFP, 10x10x2	HDMP-0450, HDMP-0450R1, HDMP-0450G, HDMP-0450GR1 HDMP-0451, HDMP-0451R1, HDMP-0451G, HDMP-0451GR1 HDMP-0452, HDMP-0452R1, HDMP-0452G
64L MQFP, 10x10x2	HDMP-0480, HDMP-0480R1, HDMP-0480G HDMP-1536A, HDMP-1536AR1, HDMP-1536AG, HDMP-1536AGR1 HDMP-1636A, HDMP-1636AR1, HDMP-1636AG, HDMP-1636AGR1 HDMP-1736
64L TQFP, 10x10x1	HDMP-T1636A, HDMP-T1636AR1, HDMP-T1636AG, HDMP-T1636AGR1
64L MQFP, 14x14x2	HDMP-1032A, HDMP-1032AR1, HDMP-1032AG, HDMP-1032AGR1 HDMP-1646A, HDMP-1646AR1, HDMP-1646AG, HDMP-1646AGR1 QDMP-1696, QDMP-1696G
64L INT-TEP-MQFP, 10x10x2	HDMP-0552, HDMP-0552G HDMP-1638, HDMP-1638R1, HDMP-1638G
64L INT-TEP-MQFP, 14x14x2	HDMP-0482, HDMP-0482R1, HDMP-0482G, HDMP-0482GR1 HDMP-1034A, HDMP-1034AR1, HDMP-1034AG, HDMP-1034AGR1
80L EDQUAD-MQFP, 14x20x2.6	HDMP-1022, HDMP-1022G, HDMP-1024, HDMP-1024G
208L TBGA, 23x23x0.9	HDMP-1685A, HDMP-1685AG, HDMP-1687, HDMP-1687G

Note: This PCN shall be used in conjunction with EOL notification issued per OBS012005-Pb-Free.

Description and Extent of Change:

- Transfer of assembly site for wire bonded packages:

From	To
Hong Kong	Dong Guan (DG) China

Reasons for Change:

Assembly supplier for above packages has announced their plan to move their assembly facilities from Hong Kong to Dong Guan (DG) China, as part of their manufacturing & test strategy.

Effect of Change on Fit, Form, Function, Quality, or Reliability:

These changes do not impact Form, Fit, Function and Reliability of the devices. Device specifications will remain the same.

The DG site uses same, process specifications, design rules, equipment/tooling and key technical resources as Hong-Kong.

Effective Date of Change:

Upon completion of transfer, process verification, and qualification expected by March '06, product shipments will begin June '06.

Parts identified as EOL per OBO012005-Pb-Free may be assembled at DG, until the EOL dates where applicable.

Device marking will be changed from Hong Kong to China to reflect country of origin.

Verification Plan:

	AEVAL # 1	*AEVAL # 2*	*AEVAL #3*	*AEVAL #4*	*AEVAL #5*
Package type	10x10x2.0 64L INT-TEP-MQFP Pb Free	14x14x2.0 64L INT-TEP-MQFP Pb Free	10x10x1.0 TQFP Pb Free	14x20x2.7 80L EDQUAD-MQFP Pb Free	23x23x0.9 208L TBGA Pb Free
Avago Tech Part#	HDMP-0552G	HDMP-0482G	HDMP-T1636AG	HDMP-1024G	HDMP-1685AG
Fab Technology	BiCMOS	HP-25-BiPolar	HP-25-BiPoloar	HP-25-BiPolar	HP-25-BiPolar
Qualification Tests:					
Preconditioning *Level 3 soak, 3x IR, 260 C peak*	22 units	22 units	22 units	22 units	22 units
Solderability Test	10 units	10 units	10 units	10 units	10 units

These changes have been reviewed and approved by Avago Technologies engineers and managers per Avago Technologies procedure: Change Control and Customer Notification, A-5962-6052-80.